Amendments to the Claims:

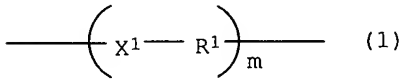
This listing of claims will replace all prior versions and listings of claims in the application:

1. (Original) A resin composition used as an adhesive bonding a semiconductor chip or a heat dissipating member comprising a filler (A), the following compound (B) and a thermal radical initiator (C), and substantially not containing a photo polymerization initiator:

Compound (B):

a compound containing a structure represented by the following formula (1) in a main chain and having at least one functional group represented by the following formula (2):

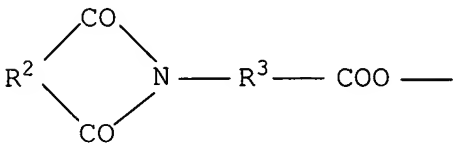
Formula (1):



(1)

wherein X^1 is –O-, -COO- or –OCOO-; R^1 is a hydrocarbon group having 1 to 6 carbons; "m" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

Formula (2):



(2)

wherein R^2 is $–C_2H_2-$ or $–C_3H_4-$; R^3 is a hydrocarbon group having 1 to 11 carbons; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

2. (Original) A resin composition according to Claim 1, wherein the filler (A) is silver powder.

3. (Amended) A resin composition according to Claim 1 ~~or 2~~, wherein X^1 of the compound (B) is –O-.

4. (Amended) A resin composition according to ~~any of Claims 1 to 3~~ Claim 1, wherein R^1 of the compound (B) is a hydrocarbon group having 3 to 6 carbons.

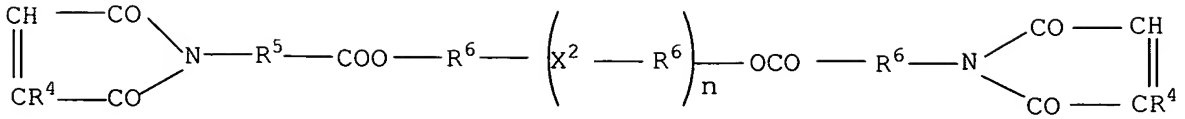
5. (Original) A resin composition according to Claim 4, wherein R^1 of the compound (B) is at least one selected from the group consisting of $-C_3H_6-$ and $-C_4H_8-$.

6. (Amended) A resin composition according to ~~any of Claims 1 to 5~~ Claim 1, wherein R^2 is $-C_2H_2-$ and R^3 is $-CH_2-$ in the compound (B).

7. (Amended) A resin composition according to ~~any of Claims 1 to 6~~ Claim 1, wherein the compound (B) has two functional groups represented by the formula (2).

8. (Amended) A resin composition according to ~~any of Claims 1 to 7~~ Claim 1, wherein the compound (B) is a ~~bismaleimide~~ bis-maleimide compound (B') represented by the following formula (3):

Formula (3):



(3)

wherein X^2 is –O-, -COO- or –OCOO-; each R^4 is hydrogen atom or a methyl group; each R^5 is a hydrocarbon group having 1 to 11 carbons; each R^6 is a hydrocarbon group having 3 to 6 carbons; "n" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

9. (Amended) A resin composition according to Claim 8, wherein X^2 of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is –O-.

10. (Amended) A resin composition according to Claim 8 ~~or 9~~, wherein R^5 of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is a hydrocarbon group not containing an aromatic group.

11. (Amended) A resin composition according to ~~any of Claims 8 to 10~~ Claim 8, wherein R^5 of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) has 1 to 5 carbons.

12. (Amended) A resin composition according to ~~any of Claims 8 to 11~~ Claim 8, wherein R^5 of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is $-CH_2-$ or $-C_5H_{10}-$.

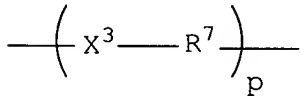
13. (Amended) A resin composition according to ~~any of Claims 8 to 12~~ Claim 8, wherein R^6 of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is at least one selected from the group consisting of $-C_3H_6-$ and $-C_4H_8-$.

14. (Amended) A resin composition according to any of ~~Claims 1 to 13~~ Claim 1, further comprising the following compound (D):

Compound (D):

a compound containing a structure represented by the formula (4) in a main chain and having at least one functional group having a polymerizable C-C unsaturated bond:

Formula (4):



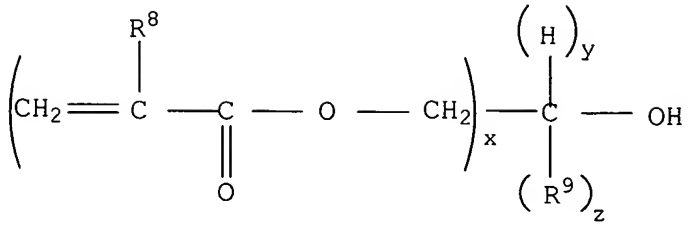
(4)

wherein X^3 is –O-, -COO- or –OCOO-; R^7 is a hydrocarbon group having 3 to 6 carbons; "p" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

15. (Amended) A resin composition according to any of ~~Claims 1 to 14~~ Claim 1, further containing the following acrylic ester compound (E):

Acrylic ester compound (E):

Formula (5):



(5)

wherein R^8 is hydrogen atom or a methyl group; R^9 is a hydrocarbon group having 1 to 3 carbons; "x", "y" and "z" are in the relationship expressed by $(x+y+z)=3$, $1 \leq x \leq 3$, $0 \leq y \leq 2$ and $0 \leq z \leq 2$; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

16. (Amended) A resin composition according to ~~Claim 15~~ Claim 1, wherein R^8 of the acrylic ester compound (E) represented by the formula (5) is a methyl group.

17. (Amended) A resin composition according to ~~Claim 15~~ Claim 1, wherein R^9 of the acrylic ester compound (E) represented by the formula (5) is a methyl group.

18. (Amended) A resin composition according to ~~Claim 16~~ Claim 1, wherein R^8 is a methyl group, R^9 is a methyl group, and $x=1$, $y=1$, and $z=1$ in the acrylic ester compound (E) represented by the formula (5).

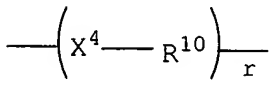
19. (Amended) A resin composition according to ~~Claim 16~~ Claim 1, wherein R^8 is a methyl group, $x=2$, $y=1$ and $z=0$ in the acrylic ester compound (E) represented by the formula (5).

20. (Amended) A resin composition according to any of ~~Claims 1 to 19~~ Claim 1, further comprising the following acrylamide compound (F):

Acrylamide compound (F):

a compound containing a structure represented by the following formula (6) in a main chain and having at least one functional group represented by the following formula (7):

Formula (6):



(6)

Formula (7):

(7)

wherein X^4 is –O-, -COO- or –OCOO-; R^{10} is a hydrocarbon group having 3 to 6 carbons; R^{11} is hydrogen atom or a methyl group; "r" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

21. (Amended) A resin composition according to ~~Claim 20~~ Claim 20, wherein R^{10} of the structure represented by the formula ~~(6)~~ (5) of the acrylamide compound ~~(F)~~ (E) is at least one selected from the group consisting of $-C_3H_6-$ and $-C_4H_8-$.

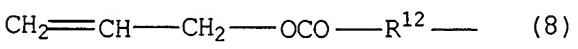
22. (Amended) A resin composition according to ~~Claim 20 or 21~~ Claim 20, wherein X^4 of the structure represented by the formula ~~(6)~~ (5) of the acrylamide compound ~~(F)~~ (E) is –O-.

23. (Amended) A resin composition according to any of ~~Claims 1 to 22~~ Claim 1, further containing the following allyl ester compound (G):

Allyl ester compound (G):

a compound having at least one functional group represented by the following formula (8):

Formula (8):



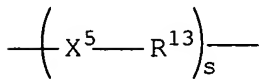
(8)

wherein R^{12} is a hydrocarbon group having 2 to 8 carbons.

24. (Original) A resin composition according to Claim 23, wherein R^{12} of the structure represented by the formula (8) of the allyl ester compound (G) does not contain an aromatic group.

25. (Amended) A resin composition according to ~~Claim 23 or 24~~ Claim 23, wherein the allyl ester compound (G) contains a structure represented by the following formula (9):

Formula (9):



(9)

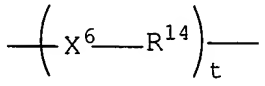
wherein X^5 is –O-, -COO- or –OCOO-; R^{13} is a hydrocarbon group having 3 to 6 carbons; "s" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

26. (Amended) A resin composition according to any of ~~Claims 1 to 25~~ Claim 1, further containing the following compound (H):

Compound (H):

a compound derived from a hydrocarbon having at least one C-C unsaturated bond in one molecule, which has a number average molecular weight of 500 to 5,000, contains a structure represented by the following formula (10) at its modified position, and has at least one functional group having a polymerizable C-C unsaturated bond:

Formula (10):



(10)

wherein X^6 is –O-, -COO- or –OCOO-; R^{14} is a hydrocarbon group having 3 to 6 carbons; "t" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

27. (Original) A resin composition according to Claim 26, wherein X^6 is –O- and R^{14} is C_4H_8 in the structure represented by the formula (10) of the compound (H).

28. (Amended) A resin composition according to Claim 26 ~~or 27~~, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is a butadiene polymer.

29. (Amended) A resin composition according to Claim 26 ~~or 27~~, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is an isoprene polymer.

30. (Amended) A resin composition according to ~~any of Claims 26 to 29~~ Claim 26, wherein the polymerizable C-C unsaturated bond of the compound (H) is a (meth)acryloyl group.

31. (Amended) A resin composition according to any of ~~Claims 1 to 30~~ Claim 1, further containing a reactive diluent (I).

32. (Original) A resin composition according to Claim 31, wherein the reactive diluent (I) is a vinyl compound which is in liquid form at room temperature other than the compounds (D) to (H).

33. (Original) A resin composition according to Claim 32, wherein the vinyl compound is a compound containing at least one (meth)acryloyl group.

34. (Amended) A resin composition according to ~~any of Claims 1 to 33~~ Claim 1, further containing a silane-based coupling agent (J).

35. (Original) A resin composition according to Claim 34, wherein the coupling agent (J) is a silane coupling agent having an S-S bond.

36. (Amended) A resin composition according to Claim 34 ~~or 35~~, wherein the coupling agent (J) further contains a silane coupling agent having a glycidyl group.

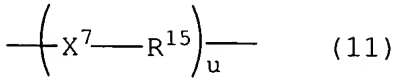
37. (Amended) A resin composition according to ~~any of Claims 1 to 36~~ Claim 1, containing a compound (K) having a glycidyl group other than the silane coupling agent having a glycidyl group.

38. (Amended) A resin composition according to ~~any of Claims 1 to 37~~ Claim 1, further containing the following compound (L) and the following compound (M):

Compound (L):

a compound containing the following structure represented by the formula (11) in a main chain and having at least one glycidyl group:

Formula (11):



(11)

wherein X^7 is –O-, -COO- or –OCOO-; R^{15} is a hydrocarbon group having 3 to 6 carbons; "u" is an integer of 2 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

Compound (M):

a compound having a functional group which can react with the glycidyl group of the compound (L).

39. (Amended) A compound according to Claim 38, wherein the repeating unit (X^7-R^{15}) of the compound (L) is the same as the repeating unit (X^1-R^1) of the compound ~~(B)~~ (M).

40. (Amended) A semiconductor device ~~produced by using the resin composition according to any of Claims 1 to 39~~ containing the resin composition according to Claim 1 as a die attach material.

41. (Amended) A semiconductor device ~~produced by using the resin composition according to any of Claims 1 to 39~~ containing the resin composition according to Claim 1 as a material for bonding a heat dissipating member.